

[Document Title] Abstract

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The objective of the present invention is, in so-called "a stacked type semiconductor device", as well as to reduce the damage caused to bonding wires in stacking, to solve problems resulting from poor accuracy in the thickness of the adhesive layer bonding semiconductor chips together, such as variation in the height of the semiconductor device, variation in the height from the substrate to the surface of the semiconductor chip in the uppermost layer and inclination of the semiconductor chip in the uppermost layer and the like.

The adhesive sheet for dicing and die bonding relating to the present invention, which achieves the above object, comprises a base material and an adhesive layer releasably laminated on said base material,

wherein said adhesive layer has a pressure sensitive adhering property at room temperature and a thermosetting property, the elastic modulus of the adhesive layer before thermosetting is 1.0×10^3 to 1.0×10^4 Pa, the melt viscosity at 120°C of the adhesive layer before thermosetting is 100 to 200 Pa·s, and the time required for the melt viscosity to reach its minimum value is 60 sec or less when the adhesive layer before thermosetting is maintained at a constant temperature of 120°C.